

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Biju Chandran et al.

Title: CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN THE  
ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY

Docket No.: 884.A27US1

Serial No.: 10/023,819

Filed: December 21, 2001

Due Date: N/A

Examiner: John B. Vigushin

Group Art Unit: 2841

Mail Stop 313(c)

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ Petition to Withdraw From Issuance Under 37 CFR 1.313(c) (1 pg.).
- ☒ Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.).
- ☒ Request for Continued Examination Transmittal (1 pg.).
- ☒ Authorization to charge Deposit Account in the amounts of \$130 for the Petition and \$790 for the RCE.

**If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.**

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: 

Atty: Lucinda G. Price

Reg. No. 42,270

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)